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NAME OF INVENTOR(S): Yoshino	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/621,771 Filing Date: 7/17/2003	
TITLE OF INVENTION: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
TI FILE NO.: TI-29448.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 11-29-04 DUE: 11/12/2004 ATTY/SECY: WDS/nc	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yoshino
Serial No: 10/621,771
Filed: 7/17/2003
For: SEMICONDUCTOR PACKAGE INSULATION FILM AND
MANUFACTURING METHOD THEREOF

Docket No: TI-29448.1
Examiner: Clark, Sheila V.
Art Unit: 2815

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AMENDMENT UNDER 37 C.F.R. § 1.115

Assistant Commissioner For Patents
Washington, DC 20231

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Dear Sir:

Responsive to the Office Action mailed August 12, 2004 in connection with the above identified application, Applicants respectfully submit the following amendments and remarks.

TI-29448.1 - 1 -